

IN THE CLAIMS:

1. (Currently Amended) A display device comprising an active matrix substrate having a peripheral portion and a driver circuit section composed of comprising a plurality of circuit elements, a plurality of polycrystalline silicon thin film transistors, a counter substrate, a liquid crystal material filled between the active matrix substrate and the counter substrate, and an individually-wired line array for supplying ~~electric power or a signal such as a clock signal and a data signal~~ a clock signal, a data signal or electric power, to ~~a~~ the plurality of circuit elements ~~comprised~~ in the driver circuit section, wherein the individually-wired line array is extended to a the peripheral portion of the active matrix substrate, ~~the display device characterized in that~~ wherein:

the peripheral portion of the active matrix substrate ~~has an insulator having a via hole and~~ comprises a multi-layer bus line-equipped section having a bus line ~~formed~~ located on the insulator, the bus line is connected to the individually-wired line array via the via hole, and the bus line ~~has~~ comprises a connecting terminal for connecting the display device to an external circuit; and

the insulator is a pre-formed resin substrate having a bus line located on a surface thereof and a via hole in the substrate.

2. (Cancelled)

3. (Currently Amended) A The display device according to claim 21, wherein the resin substrate ~~is composed of~~ comprising an aramid-epoxy resin.

4. (Currently Amended) A The display device according to claim 2 1, wherein ~~an~~ the via hole is filled with electrically conductive paste ~~is filled in the via hole.~~

5. (Currently Amended) A display device according to claim 2 1, wherein the resin substrate ~~has~~ is a multi-layer structure ~~having~~ comprising a plurality of layers in which a said bus line is ~~provided~~ located on a surface of an inner layer thereof as well as on a surface of the ~~uppermost~~ outermost layer thereof, and the bus lines are selectively connected to each other via a via hole ~~formed~~ in each of the layers to form a three-dimensional wiring structure.

6. (Currently Amended) A The display device according to claim 4, wherein the electrically conductive paste partially protrudes from a lower opening of the via hole, and the active matrix substrate and the resin substrate are bonded together with the protruding portion of the electrically conductive paste.

7. (Currently Amended) A The display device according to claim 5, wherein an electrically conductive paste ~~is filled in~~ fills the via hole; the electrically conductive paste protrudes from a lower opening of the via hole; and the electrically conductive paste partially protrudes from a ~~lower~~ an opening of the via hole, and the active matrix substrate and the resin substrate are bonded together with the protruding portion of the electrically conductive paste.

8. (Currently Amended) A The display device according to claim 2 1, wherein the resin substrate and the active matrix substrate are bonded with an adhesive ~~composed of~~ comprising a material having a thermoplastic property.

9. (Currently Amended) A The display device according to claim 2 1, wherein the resin substrate and the active matrix substrate are bonded with an adhesive ~~composed of~~ comprising an anisotropic conductive resin or a silver paste.

10. (Currently Amended) A The display device according to claim 2 1, wherein the resin substrate is a film substrate, and is detachably bonded to the active matrix substrate.

11. (Currently Amended) A The display device according to claim 10, wherein the film substrate is made of a resin comprising polyimide or epoxy.

12. (Currently Amended) A The display device according to claim 2 1, ~~wherein~~ further comprising a semiconductor chip ~~comprised in the~~ of an external circuit, said semiconductor chip being is mounted on the resin substrate and is connected to the bus line.

13. (Currently Amended) A The display device according to claim 12, wherein the semiconductor chip is buried in the via hole.

14. (Currently Amended) A The display device according to claim 1, wherein the bus line in the multi-layer bus line-equipped section is a thick film ~~formed by printing.~~

15. (Currently Amended) A The display device according to claim 14, wherein the insulator in the multi-layer bus line-equipped section is a thick film ~~formed by printing.~~

16. (Currently Amended) A display device comprising an active matrix substrate having a peripheral portion and a driver circuit section comprising a plurality of circuit elements, a plurality of polycrystalline silicon thin film transistors, a counter substrate, a liquid crystal material filled between the active matrix substrate and the counter substrate, and an individually-wired line array for supplying a clock signal, a data signal or electric power, to ~~a~~ the plurality of circuit elements ~~comprised~~ in the driver circuit section, wherein the individually-wired line array is extended to a the peripheral portion of the active matrix substrate, ~~the display device~~ ~~characterized in that~~ wherein:

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to the individually-wired line array is buried in the organic resin layer.

18. (Canceled)

19. (Currently Amended) A The display device according to claim ~~18~~ 17, wherein the bus line is an electrically conductive thermosetting resin ~~formed by screen printing~~.

20. (Currently Amended) A The display device according to claim 16, wherein the bus line is a pre-formed metal fine wire.

21. (Currently Amended) A The display device according to claim 17, wherein the bus line is a pre-formed metal fine wire.

22. (Currently Amended) A The display device according to claim 16, wherein the bus line is produced by plating.

23. (Currently Amended) A The display device according to claim 17, wherein the bus line is produced by plating.

24. (Cancelled)

25. (Currently Amended) A The display device according to claim 23, wherein the bus line ~~produced by plating forms~~ is a layered structure comprising a copper foil layer, a copper plating layer, and a gold-nickel plating layer.

26. (Currently Amended) A The display device according to claim 16, wherein the bus line is formed by selective depositing in which a thin, electrically conductive layer is formed in advance and a plurality of different metal layers are ~~selectively~~ successively deposited on the electrically conductive layer.

27. (Currently Amended) A The display device according to claim 17, wherein the bus line is formed by selective depositing in which a thin, electrically conductive layer is formed in advance and a plurality of different metal layers are ~~selectively~~ successively deposited on the electrically conductive layer.

28. (Currently Amended) A The display device according to claim 1, wherein, in place of the liquid crystal, a rare gas is

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~~filled~~ located between the substrates, and the rare gas  
~~undergoes~~ for forming a plasma discharge to perform a display  
operation.

29. - 38. (Cancelled)